

BRBT0808SWDP

Rev.A Nov.-2023



蓝箭电子
BLUE ROCKET ELECTRONICS

DATA SHEET

TO-252

Triac in a TO-252 Plastic Package.



Parameter	Symbol	Rating	Unit
Repetitive peak off-state/reverse voltages($T_j=125^\circ\text{C}$)	$V_{\text{DRM}}/V_{\text{RRM}}$	800	V
RMS on-state current($T_c=110^\circ\text{C}$)	$I_{\text{T(RMS)}}$	8	A
Non repetitive surge peak on-state current(full cycle, $T_j=25^\circ\text{C}$)	$I_{\text{TSM}(t=20\text{ms})}$	80	A
I^2t value for fusing($T_j=25^\circ\text{C}$)	$I^2t_{(tp=10\text{ms})}$	32	A^2s
Critical rate of rise of on-state current ($I_G=2I_{\text{GT}}$, $f=120\text{Hz}$ $T_j=125^\circ\text{C}$)	di/dt I-II-III	50	A/s
Peak gate current($t_p=20\text{ s}$ $T_j=125^\circ\text{C}$)	I_{GM}	4.0	A
Average gate power dissipation($T_j=125^\circ\text{C}$)	$P_{\text{G(AV)}}$	1.0	W
Operating junction temperature range	T_j	-40 125	
Storage junction temperature range	T_{stg}	-40 150	
Junction to ambient(AC)	$R_{\text{th(j-a)}}$	100	/W
Junction to case for(AC)	$R_{\text{th(j-c)}}$	3.1	

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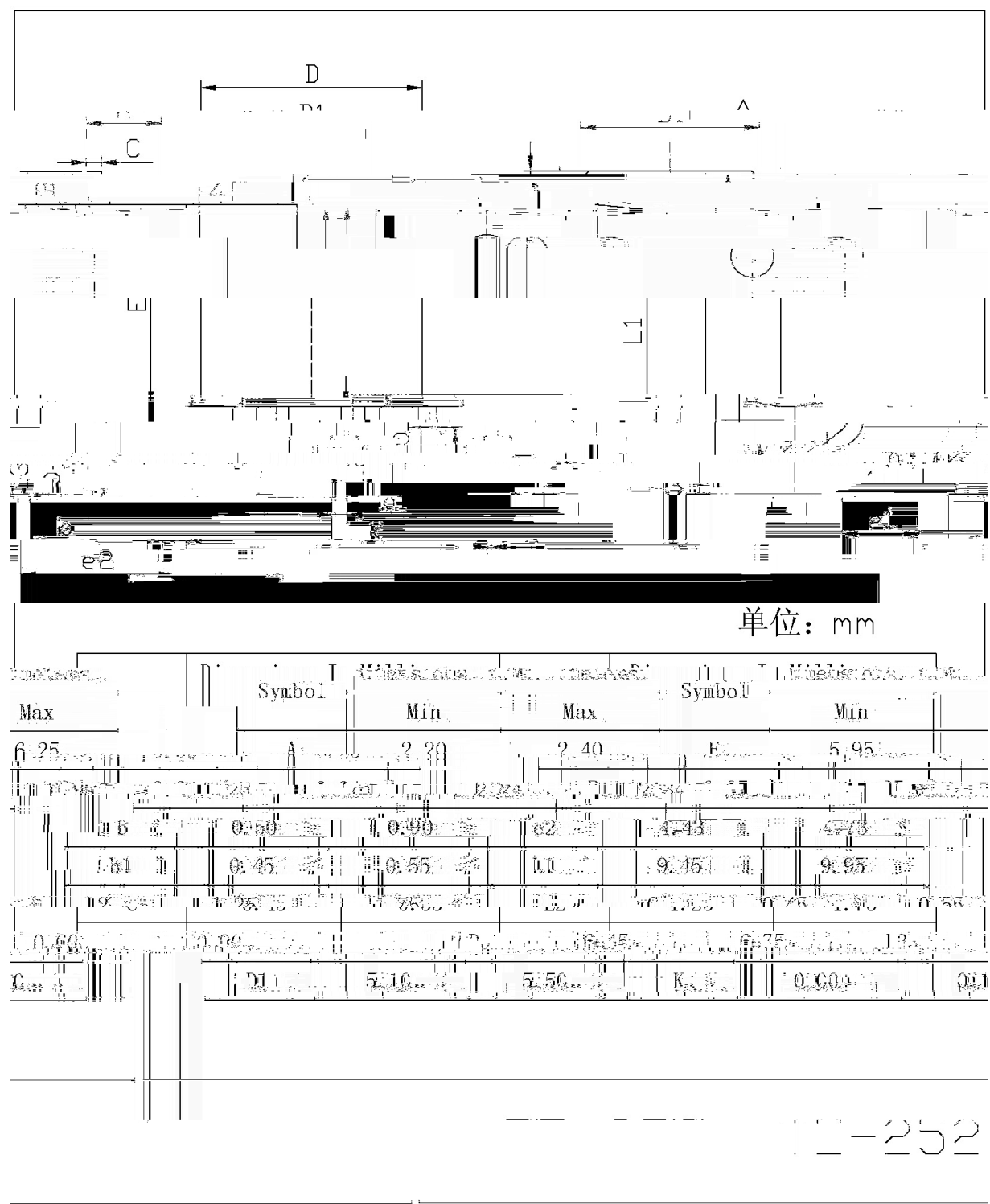
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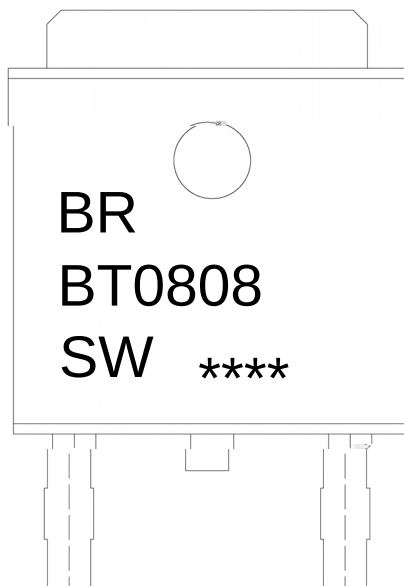
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/ Package Dimensions



/ Marking Instructions



BR

BT0808

SW

I_{GT}

Note:

BR: Company Code

BT0808: Product Type Code

SW: I_{GT} Bracket code

****: Lot No. Code, code change with Lot No


() / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

- | | | | |
|---|---------|-----------|---|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | 2 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec
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/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit X mm ³)	
	2, e	O-252	2, 2TD-4	Tc(5,08343	TD.2200c(6TD-93601(30,8343			T343	TD88w[1359.48
TO-252									